

ABSTRACT

A system for removing heat from an encased electronic device. The system includes a thermal ground, conduction pathways thermally coupling heat-producing elements of the device to the thermal ground so that the thermal ground receives heat produced by the heat-producing elements, and a heat dissipation element thermally coupled to the thermal ground and configured to transfer heat from the thermal ground to an environment outside the device. The conduction pathways and heat dissipation element provide a capacity to remove heat from the encased electronic device such that heat removal by convection from the heat-producing elements is not required.

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